CD54AC112, CD74AC112 DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

SCHS325 - JANUARY 2003

- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply Voltage
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ±24-mA Output Drive Current
 Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

CD54AC112...F PACKAGE CD74AC112...E OR M PACKAGE (TOP VIEW) 1CLK [1K **∏** 15 1 1 CLR 1J [14 2 2 CLR 13 2CLK 1Q 🛮 5 12 2K 1Q 11 **∏** 2J $2\overline{Q}$ 10 2PRE 9 2Q GND 8

description/ordering information

The 'AC112 devices contain two independent J-K negative-edge-triggered flip-flops. A low level at the preset (\overline{PRE}) or clear (\overline{CLR}) inputs sets or resets the outputs, regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the J and K inputs meeting the setup-time requirements is transferred to the outputs on the negative-going edge of the clock pulse (CLK). Clock triggering occurs at a voltage level and is not directly related to the fall time of the clock pulse. Following the hold-time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by tying J and K high.

ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74AC112E	CD74AC112E
_55°C to 125°C	SOIC – M	Tube	CD74AC112M	AC112M
-55 C to 125 C	SOIC - IVI	Tape and reel	CD74AC112M96	ACTIZIVI
	CDIP – F	Tube	CD54AC112F3A	CD54AC112F3A

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



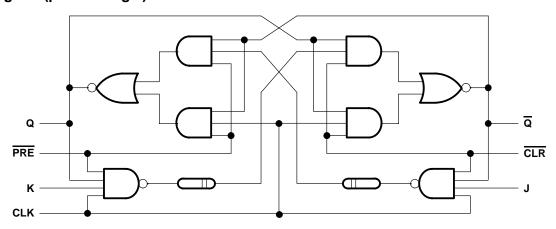
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FUNCTION TABLE (each flip-flop)

		INPUTS			OUTI	PUTS
PRE	CLR	CLK	J	K	Q	Q
L	Н	Х	Χ	Х	Н	L
Н	L	X	Χ	X	L	Н
L	L	X	Χ	X	н†	H [†]
Н	Н	\downarrow	L	L	Q_0	\overline{Q}_0
Н	Н	\downarrow	Н	L	Н	L
Н	Н	\downarrow	L	Н	L	Н
Н	Н	\downarrow	Н	Н	Toggle	
Н	Н	Н	Χ	Χ	Q ₀	\overline{Q}_0

[†] Output states are unpredictable if PRE and CLR go high simultaneously after both being low at the same time.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 6 V
Input clamp current, I_{IK} ($V_I < 0 \text{ V or } V_I > V_{CC}$) (see Note 1)	
Output clamp current, I_{OK} ($V_O < 0 \text{ V or } V_O > V_{CC}$) (see Note 1)	
Continuous output current, I_O ($V_O > 0$ V or $V_O < V_{CC}$)	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 2): E package	67°C/W
M package	73°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

				25°C	–55°C to 125°C		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
Vcc	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V
	V _{IH} High-level input voltage	V _{CC} = 1.5 V	1.2		1.2		1.2		
VIH		V _{CC} = 3 V	2.1		2.1		2.1		V
		V _{CC} = 5.5 V	3.85		3.85		3.85		
		V _{CC} = 1.5 V		0.3		0.3		0.3	
VIL	Low-level input voltage	V _{CC} = 3 V		0.9		0.9		0.9	V
		V _{CC} = 5.5 V		1.65		1.65		1.65	
٧ _I	Input voltage		0	Vcc	0	VCC	0	VCC	V
٧o	Output voltage		0	Vcc	0	VCC	0	VCC	V
loh	High-level output current	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-24		-24		-24	mA
l _{OL}	Low-level output current	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		24		24		24	mA
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 1.5 \text{ V to 3 V}$		50		50		50	ns/V
ΔυΔν	input transition rise of fall fate	V _{CC} = 3.6 V to 5.5 V		20		20		20	115/ V

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vcc	T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX	1	
			1.5 V	1.4		1.4		1.4			
		I _{OH} = -50 μA	3 V	2.9		2.9		2.9			
			4.5 V	4.4		4.4		4.4			
VOH	$V_I = V_{IH}$ or V_{IL}	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.4		2.48		V	
		I _{OH} = -24 mA	4.5 V	3.94		3.7		3.8			
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V			3.85					
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V					3.85	5		
			1.5 V		0.1		0.1		0.1		
		$I_{OL} = 50 \mu A$	3 V		0.1		0.1		0.1		
			4.5 V		0.1		0.1		0.1		
V_{OL}	$V_I = V_{IH}$ or V_{IL}	I _{OL} = 12 mA	3 V		0.36		0.5		0.44	V	
		I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44		
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65				
		I _{OL} = 75 mA†	5.5 V						1.65		
IĮ	$V_I = V_{CC}$ or GND		5.5 V		±0.1		±1		±1	μΑ	
ICC	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		4		80		40	μΑ	
Ci			-		10		10		10	pF	

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.



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timing requirements over recommended operating free-air temperature range, V_{CC} = 1.5 V (unless otherwise noted)

				–55°C to 125°C		–40°C to 85°C	
			MIN	MAX	MIN	MAX	
fclock	Clock frequency			8	,	9	MHz
	Pulse duration	CLK high or low	63		55		
t _W	ruise duration	CLR or PRE low	56		49		ns
t _{su}	Setup time, before CLK↓	J or K	50		44		ns
th	Hold time, after CLK↓	J or K	0		0		ns
t _{rec}	Recovery time, before CLK↓	CLR↑ or PRE↑	31		27		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted)

			–55° 125		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
fclock	Clock frequency			71		81	MHz
	Pulse duration	CLK high or low	7		6		no
t _W	ruise duration	CLR or PRE low	6.3		5.5		ns
t _{su}	Setup time, before CLK↓	J or K	5.6		4.9		ns
t _h	Hold time, after CLK↓	J or K	0		0		ns
t _{rec}	Recovery time, before CLK↓	CLR↑ or PRE↑	3.5		31		ns

timing requirements over recommended operating free-air temperature $_0$ range, V $_{CC}$ = 5 V \pm 0.5 V (unless otherwise noted)

			–55° 125		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency			100		114	MHz
	t _w Pulse duration	CLK high or low	5		4.4		20
۱W		CLR or PRE low	4.5		3.9		ns
t _{su}	Setup time, before CLK↓	J or K	4		3.5		ns
t _h	Hold time, after CLK↓	J or K	0		0		ns
t _{rec}	Recovery time, before CLK↓	CLR↑ or PRE↑	2.5		2.2		ns

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 1.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C		–40°C to 85°C		UNIT	
	(1141 01)	(6611 61)	MIN	MAX	MIN	MAX		
f _{max}			8		9		MHz	
.	CLK	Q or $\overline{\mathbb{Q}}$		129		117		
^t PLH	CLR or PRE			153		139	ns	
+-	CLK	0 22 0		129		117		
PHL	tPHL CLR or PRE Q or Q		153		139	ns		

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM TO (OUTPUT)	_	–55°C to 125°C		–40°C to 85°C		UNIT
		(6611 61)	MIN	MAX	MIN	MAX	
f _{max}			71		81		MHz
+	CLK	Q or Q	3.6	14.4	3.7	13.1	no
^t PLH	CLR or PRE		4.3	17.1	4.4	15.5	ns
t =	CLK	Q or Q	3.6	14.4	3.7	13.1	no
^t PHL	CLR or PRE		4.3	17.1	4.4	15.5	ns

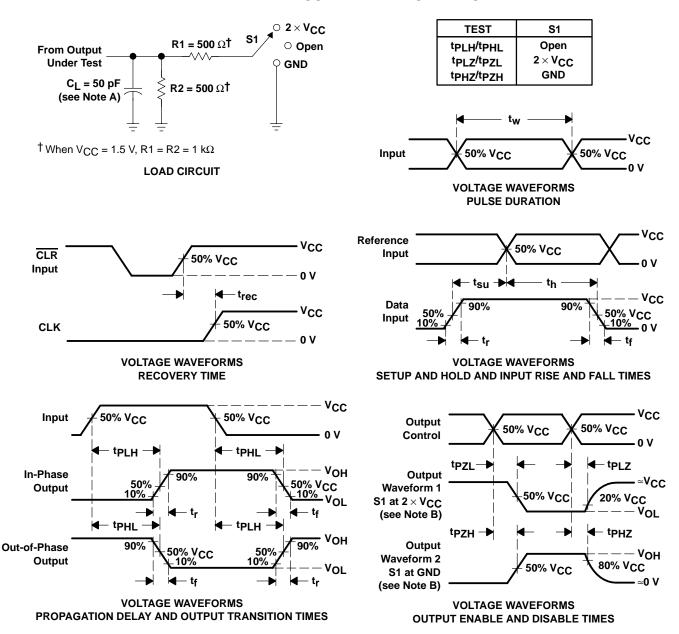
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C		–40°C to 85°C		UNIT
	(1141 01)	(6611 61)	MIN	MAX	MIN	MAX	
f _{max}			100		114		MHz
+-	CLK	Q or $\overline{\mathbb{Q}}$	2.6	10.3	2.7	9.4	no
^t PLH	CLR or PRE		3.1	12.2	3.2	11.1	ns
+=	CLK	Q or Q	2.6	10.3	2.7	9.4	20
^t PHL	CLR or PRE	Q 01 Q	3.1	12.2	3.2	11.1	ns

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TYP	UNIT
Cpd		56	pF

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_Γ = 3 ns, t_f = 3 ns. Phase relationships between waveforms are arbitrary.
 - D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
 - E. The outputs are measured one at a time with one input transition per measurement.
 - F. tpLH and tpHL are the same as tpd.
 - G. tpzL and tpzH are the same as ten.
 - H. tpLZ and tpHZ are the same as tdis.
 - I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
CD54AC112F3A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54AC112F3A
CD54AC112F3A.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54AC112F3A
CD74AC112E	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74AC112E
CD74AC112E.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74AC112E
CD74AC112M	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-55 to 125	AC112M
CD74AC112M96	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC112M
CD74AC112M96.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC112M

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF CD54AC112, CD74AC112:

• Military : CD54AC112

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC112M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device		Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	CD74AC112M96	SOIC	D	16	2500	353.0	353.0	32.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD74AC112E	N	PDIP	16	25	506	13.97	11230	4.32
CD74AC112E	N	PDIP	16	25	506	13.97	11230	4.32
CD74AC112E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74AC112E.A	N	PDIP	16	25	506	13.97	11230	4.32

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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